

ABSTRACT

5 **METHOD OF FORMING THREE-DIMENSIONAL WIRE LOOPS AND**
 WIRE LOOPS FORMED USING THE METHOD

10 The invention provides a method of bonding wire between first and second
 bonding points with a bonding tool. It comprises the steps of forming a first
 bond at the first bonding point with the bonding tool, forming a first kink
 located over the first bond, and moving the bonding tool to a first position
 spaced from the first kink by a predetermined distance to release a length of
 wire from the bonding tool. It further comprises the step of moving the bonding
 tool in a direction away from the second bonding point to a second position
15 which is outside a plane comprising the first bonding point, the second
 bonding point, and the first kink. It also comprises the steps of forming a
 second kink which lies outside the plane, and moving the bonding tool to the
 second bonding point to form a second bond.

20 (Fig. 2b)